

13th November (the 1st day)

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<General Session>ROYAL				
Time				
10:00-10:10	Greeting Yoichi Ngasima, General Manager, CYBERNET SYSTEMS CO.,LTD.			
10:10-10:50	ANSYS, Inc Vision, Strategy and Progress Jim Cashman, CEO, ANSYS, Inc. ★			
10:50-11:35	ANSYS Technology Roadmap Dale Ostergard, Director of Workbench Physics, Mechanical Business Unit, ANSYS, Inc. ★			
11:35-11:50	Introduction of ANSYS Technical Seminar CYBERNET SYSTEMS CO.,LTD Tomohiro Ishida			
11:50-13:00	Lunch			
Time	<Track1>ROYAL A	<Track2>ROYAL B	<Track3>ROYAL C	<Track4>CROWN
13:00-13:50	FSI analysis in a Piezo Inkjet Head - Follow-up Report - CYBERNET SYSTEMS CO.,LTD Syunsuke Masuda	The present conditions and future of nonlinear multi-scale analysis Tohoku University Kenjiro Tarada	Stress Analysis of Harp in HRSG Doosan Heavy Industries & Construction Chong Chae-Hon ★	ANSYS Workbench Dynamic Analysis CYBERNET SYSTEMS CO.,LTD Takahiro Miura
13:50-14:00	Coffee break			
14:00-14:50	Suggestion for FSI analysis using Icepak and ANSYS CYBERNET SYSTEMS CO.,LTD Syunsuke Masuda	Nonlinear multi-scale analysis with ANSYS and computational material testing NITTO BOSEKI CO.,LTD. Norio Hirayama	FE-Applications in Aircraft Structure Analysis using ANSYS and LS-DYNA CAD-FEM GmbH Wilhelm Rust ★	Tips of Meshing in ANSYS Workbench CYBERNET SYSTEMS CO.,LTD Toru Nishimori
14:50-15:10	Coffee break			
15:10-16:00	Robust Design with OPTIMUS and Icepak CYBERNET SYSTEMS CO.,LTD Satoshi Furui	Approach to improve accuracy in the structural analysis of semiconductor package IBM JAPAN, Ltd. Toshihiko Nishio	Introduction of ANSYS Rezone CYBERNET SYSTEMS CO.,LTD Masahiro Matsumoto	Customize techniques of ANSYS Workbench CYBERNET SYSTEMS CO.,LTD Yasuhiro Miyado
16:00-16:10	Coffee break			
16:10-17:00	Sequential analysis for SIMBLOW and ANSYS PLAMEDIA CORPORATION Keiichi Saito			Robust Design with ANSYS Workbench CYBERNET SYSTEMS CO.,LTD Yasuhiro Miyado
17:20-19:00	Reception Party			

★ English Session

14th November (the 2st day)

Time	<Track1> ROYAL A	<Track2> ROYAL B	<Track3> ROYAL C	<Track4> CROWN
10:00-10:30	Analysis of blood vessel vibration generation mechanism by FSI Toin University of Yokohama Toshio sato	Analysis of bimetal which formed for snap action UBUKATA INDUSTRIES CO.,LTD. Takao Tsuji	Mathematical Modeling for Physical Phenomenon in Material Relevant CAE Covalent Materials Corporation Pei Shin	Bifurcation Path Tracing of Buckling-restrained Braces Tokyo Institute, Polytechnic University Yoshio Kuriyama
10:30-10:40				
10:40-11:10	FSI Analysis for Flexible Wall Brother Industries, Ltd. Hiroyuki Ishikawa	Analysis of Composite Tank Murata Machinery, Ltd. Yusuke Yshimura	Multiscale simulation of thin-film strength Hitachi, Ltd. Yasutaka Ookura	The Influence of the shear rigidity of a scaffolding frame and a horizontal frame on a scaffold's buckling mode National Institute of Occupational Safety and Health Hiroki Takahashi
11:10-11:20				
11:20-11:50	Electro magnetic and heat conductive FE analysis on high frequency tube welding process JFE Steel Corporation Takatoshi Okabe	Example of CAE in pipe processing Rinnai Corporation Mitsutoshi Minatani	CAE use case in ITOKI ITOKI CORPORATION Takeki Kimura	Development of baseball pitching machine with rollers using dynamic finite element analysis Kanazawa University Shinobu Sakai
11:50-12:00				
12:00-12:30	Optimize of Spot Welding Simulation Fuji Heavey Industries Ltd, Kenei Shin	Structural Analysis of Micro Physical Sensors by ANSYS Osaka University Masayuki Sougawa	Analysis in mind:a proposal on an attitude toward CAE AISIN SEIKI Co.,Ltd Motohiro Okade	Stress analysis of bellows type expansion joint by FEM and fatigue-life prediction Doshisha University Hiroyuki Miyamoto
12:30-13:40	Lunch			
13:40-14:10	Various Examples of Finite Element Analysis on Bolted Flange-Gasket Connections Toyo Engineering Corporation Satoshi Nagata	Reliability Evaluation for Solder Bumps in a Flip Chip Package by Viscoelastic Analysis of an Underfill Resin NEC Corporation Takashi Kondo	The action to promote inflection of the simulation by the designer SANYO Electric Co., Ltd. Masayuki Hirate	Plastic Fatigue Life Estimation of Steel Bridge Pier Base Joint under Seismic Loading KANSAI University Graduate School Yuji Nishigaki
14:10-14:20				
14:20-14:50	Fitness-For-Service assessment of pressure equipment in chemical plant SUMITOMO CHEMICAL Co., Ltd. Takuyou Kaida	The thermal stress analysis for a semiconductor packaging IBM Japan, Ltd. Toru Nakanishi	Introduction of ANSYS DesignSpace and designer-led CAE implementation NEC Access Technica,Ltd Tsuyoshi Sugioka	Development of High-performance Machine Tool s Spindle System by Optimum Arrangement of Low Density and High Rigidity Material Tottori University Kazutake Uehara
14:50-15:10	Coffee break			
15:10-15:40	Creep Analysis using Special evaluation factor calculations regarding Inlet Cover Model Fuji Electric Systems Co.,Ltd. Tetsu Takano	Mechanical Issue in Semiconductor Packaging. Texas Instruments Japan Limited Masazumi Amagai		Design of electrode pattern for Electro-rheological Gel Keio University Masayuki Tanaka
15:40-15:50				
15:50-16:20	Study of Reduction regarding Condenser's model weight Fuji Electric Systems Co.,Ltd Hiroatsu Kubo	Numerical simulation of non-steady heat conduction during induction line heating process Graduate School of Engineering, Osaka University Naoki Oosawa	Introduction of Ultra-Large-Scale Acoustic-Analysis Program "WAON" CYBERNET SYSTEMS CO.,LTD Yohei Furuta	Superelastic Analysis of Shape Memory Devices under Combined University of Tokyo Dae-Gon CHOI·Yutaka Toi
16:20-16:30				
16:30-17:00	The FEM application in HDD suspension design NHK SPRING CO., LTD. Kenichi Takigawa	Analysis on thermal stress of radiant tubes used in the furnace JFE Techno-Research Corporation Naotake Yoshihara	Lately Report for Vibration Control Research Using ANSYS CYBERNET SYSTEMS CO.,LTD Shinichi Ishizuka	Finite element analysis of two-dimensional electrochemical-mechanical response of ionic conducting polymer-metal composites beams University of Tokyo Woo-Sang JUNG·Yutaka Toi

Category	
Thermal	
Multiphysics	CAE implementation
Structural	Material